IN THE SPECIFICATION:

Please amend the specification as follows:

Please substitute the paragraph beginning at page 1, line 6, with the following.

-- The present invention relates to a moving apparatus, an exposure apparatus, and a device manufacturing method. --

Please substitute the paragraph beginning at page 3, line 1, with the following.

-- To decrease the vibration of the apparatus caused by the reaction force, a moving apparatus as shown in Fig. 6 is proposed. As shown in Fig. 6, a conventional moving apparatus has a stage 51 and a movable body (to be referred to as a "counter" hereinafter) 52 for canceling the reaction force. The stage 51 and counter 52 are driven by feedback control controlling a position in the Y direction, and a target value is given such that the ratio of the moving distance of the stage 51 in the Y direction to that of the counter 52 in the Y direction is substantially constant. This improves the canceling efficiency for the reaction force of the stage 51. --

Please substitute the paragraph beginning at page 4, line 13, with the following.

-- A preferred embodiment of the present invention preferably comprises a feed forward compensator which controls the second actuator on the basis of a signal supplied to the first actuator or a physical quantity of the movable element. --

Please substitute the paragraph beginning at page 5, line 17, and ending on page 6, line 2, with the following.

-- A second aspect of the present invention relates to an exposure apparatus, characterized by comprising an optical system which projects exposure light, to be irradiated to a master having a pattern, onto a substrate, a stage which can move while holding the substrate or the master, a first actuator having a movable element and a stator, the movable element being connected to the stage, a second actuator which drives the stator in the Y direction, and a third actuator which drives the stator in the X and θ direction, wherein the third actuator drives the stator in a direction to suppress rotation of the stator which accompanies movement of the movable element. --

Please substitute the paragraph beginning at page 6, line 3, with the following.

-- A third aspect of the present invention relates to a semiconductor device manufacturing method, characterized by comprising an applying step of applying a photosensitive material on a substrate, an exposure step of transferring a pattern onto the substrate, applied with the photosensitive material in the applying step, by utilizing the above exposure apparatus, and [[an]] a developing step of developing the photosensitive material on the substrate where the pattern has been transferred in the exposure step. --

Please substitute the paragraph beginning at page 9, line 10, with the following.

-- One or a plurality of interferometers (not shown) ~~are~~ is provided to control the moving apparatus, and can position the movable elements 2 and 2′ or movable portion 3 with reference to the reference structure 4. Similarly, an interferometer (not shown) for measuring the positions of the stators 1 and 1′ is provided to position the stators 1 and 1′ which move within a plane. In the above manner, a movable body 300 serving as a stage having the movable portion 3 (including the top plate 5 provided on it) and the movable elements 2 and 2′ can move in the Y direction in a non-contact manner with the flat guide surface 6. --

Please substitute the paragraph beginning at page 10, line 8, with the following.

-- As described above, the reaction force during acceleration and deceleration which acts on the movable body 300 when it moves can be absorbed by the stators 1 and 1′. The reaction force is converted into kinetic energy when the stators 1 and 1′ (reaction force movable portion), which have received the reaction force, move. Although two stators are provided in this case, the present invention is not limited to this. The number of stators may be one, or three or more. --

Please substitute the paragraph beginning at page 10, line 27, and ending on page 11, line 8, with the following.

-- When the masses of the stators 1 and 1′ are increased to be sufficiently larger than the mass of the movable body 300 including the movable portion 3, and the like, the movable range of the stators 1 and 1′ can be limited to be small. This enables downsizing of the apparatus, and

reduces the floor area of the semiconductor factory, thus contributing to the reduction of the construction cost of the entire semiconductor factory. --

Please substitute the paragraph beginning at page 20, line 21, with the following.

-- As described above, according to the preferred embodiment of the present invention, when the signal used in the control system for the movable portion is fed forward to a control system for the stators, swing, rotation and the like, of the stators which occur due to acceleration of the movable elements, can be suppressed. --

Please substitute the paragraph beginning at page 22, line 2, with the following.

-- The exposure apparatus may perform scanning and exposure of transferring a predetermined region of the pattern of a master onto a substrate by moving and scanning both the master and substrate with respect to an optical system. In this case, the exposure apparatus can drive at least one of the master and substrate during scanning by means of a stage provided to the moving apparatus according to any preferred embodiment of the present invention. Ultraviolet rays may be used as the exposure light. In this case, as the ultraviolet rays, for example, a laser beam from a fluorine excimer laser, an ArF excimer laser, or the like, which uses a laser as the light source, is preferably used. --

Please substitute the paragraph beginning at page 22, line 16, and ending on page 23, line 10, with the following.

-- A semiconductor device manufacturing process utilizing the above exposure apparatus will be described. Fig. 8 is a flow chart of the flow of the overall semiconductor device manufacturing process. In step 1 (circuit design), circuit design of a semiconductor device is performed. In step 2 (mask fabrication), a mask is fabricated based on the designed circuit pattern. In step 3 (wafer fabrication), a wafer is manufactured by using a material such as silicon. In step 4 (wafer process), called a pre-process, an actual circuit is formed on the wafer by lithography using the prepared mask and wafer. In step 5 (assembly), called a post-process, a semiconductor chip is formed by using the wafer fabricated in step 4, and includes processes such as an assembly process (dicing and bonding) and a packaging process (chip encapsulation). In step 6 (inspection), inspections such as the operation confirmation test and durability test of the semiconductor device fabricated in step 5 are performed. After these steps, the semiconductor device is completed, and shipped (step 7). --